

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	09892225			
<b>Filing Date:</b>	25-Jun-2001			
<b>Title of Invention:</b>	Semiconductor device and fabrication method therefor			
<b>First Named Inventor:</b>	Shunpei Yamazaki			
<b>Filer:</b>	John F. Hayden/Tawana N. Lefeged			
<b>Attorney Docket Number:</b>	07977/279001/US5023/5025			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	1202	14	50	700
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 1 month with \$0 paid	1251	1	120	120
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>1000</b>